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<b>Application Number</b>	10/023,819
Filing Date	December 21, 2001
First Named Inventor	Chandran, Biju
Group Art Unit	2827 2841
Examiner Name	Vigushin, John

Attorney Docket No: 884.A27US1

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Paper No. 1004

**EXAMINER** 

John B. Vogistin

DATE CONSIDERED

DERED April 08,2005

Substitute Disclosure Statement Form (PTO-1449)

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